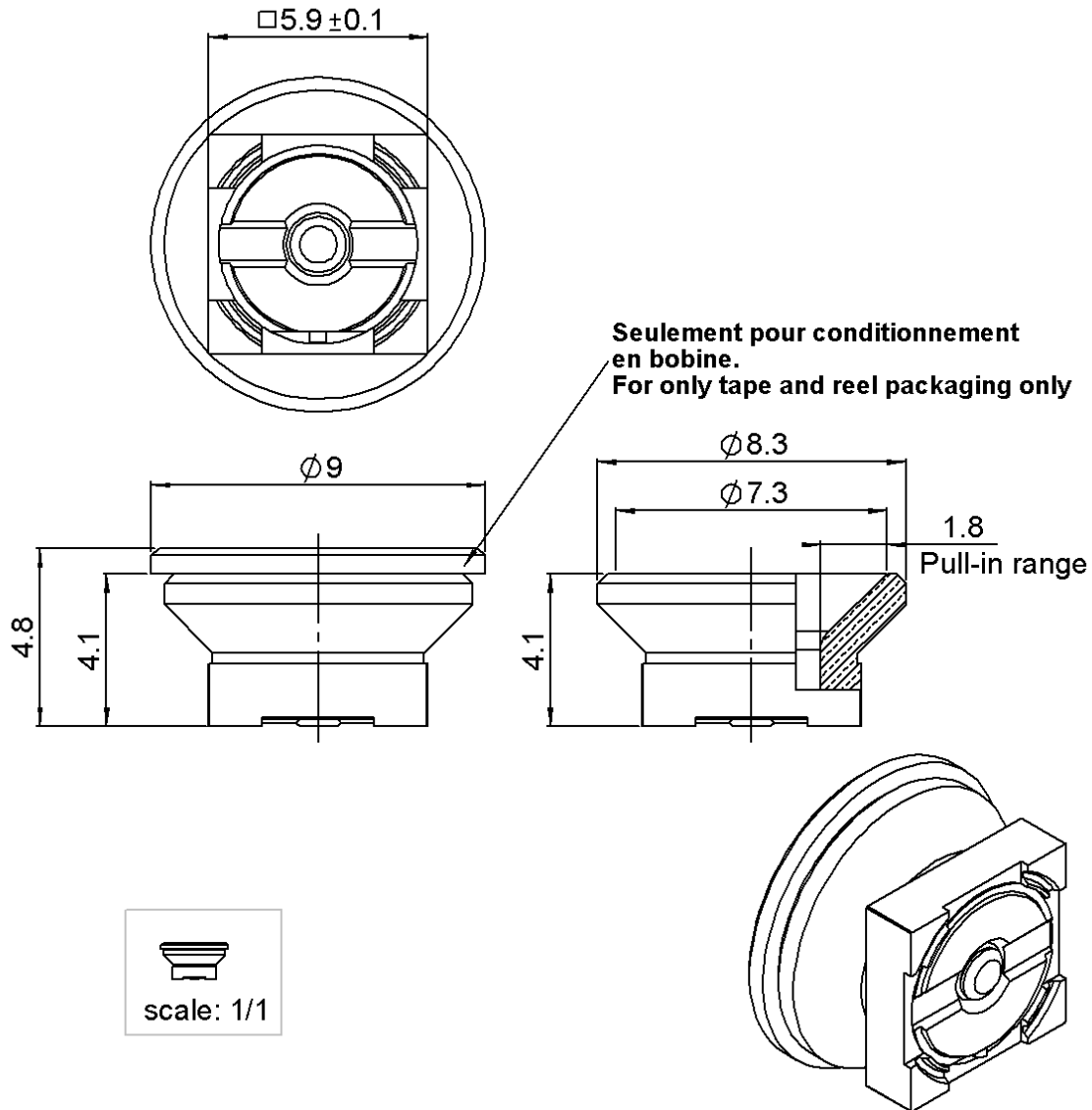


**SMT JACK RECEPTACLE**

**R223.424.870**

**REEL OF 750**

Series : MMBX



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (µm)
BODY	BRASS	NPGR
CENTER CONTACT	BRASS	NPGR
OUTER CONTACT		
INSULATOR	LIQUID CRYSTAL POLYMER	
GASKET		
OTHERS PARTS	PTFE	
-	-	-
-	-	-

Issue : 0851 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



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**PACKAGING**

**SPECIFICATION**

Standard	Unit	Other
<b>750</b>	<b>'W' option</b>	<b>Contact us</b>

**ELECTRICAL CHARACTERISTICS**

**ENVIRONMENTAL**

Impedance	<b>50</b>	$\Omega$
Frequency	<b>0-12.4</b>	GHz
VSWR	<b>1.065*</b> + <b>0,0000</b>	x F(GHz) Maxi
Insertion loss	<b>0.12</b>	$\sqrt{F}$ (GHz) dB Maxi
RF leakage	- ( <b>100**</b>	- F(GHz)) dB Maxi
Voltage rating	<b>330</b>	Veff Maxi
Dielectric withstanding voltage	<b>1000</b>	Veff mini
Insulation resistance	<b>1000</b>	M $\Omega$ mini

Operating temperature	<b>-55/+155</b>	$^{\circ}$ C
Hermetic seal	<b>NA</b>	Atm.cm3/s
Panel leakage	<b>NA</b>	

**OTHER CHARACTERISTICS**

Assembly instruction

Others :

\*\*to 6 GHz

\*\*interface MMBX only up to 2.5GHz

PCB to PCB -45dB up to 2.5 GHz

**MECHANICAL CHARACTERISTICS**

Center contact retention		
Axial force – Mating end	<b>10</b>	N mini
Axial force – Opposite end	<b>10</b>	N mini
Torque	<b>NA</b>	N.cm mini
Recommended torque		
Mating	<b>NA</b>	N.cm
Panel nut	<b>NA</b>	N.cm
Mating life	<b>100</b>	Cycles mini
Weight	<b>0,8900</b>	g

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**RADIALL** 

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**REEL OF 750**

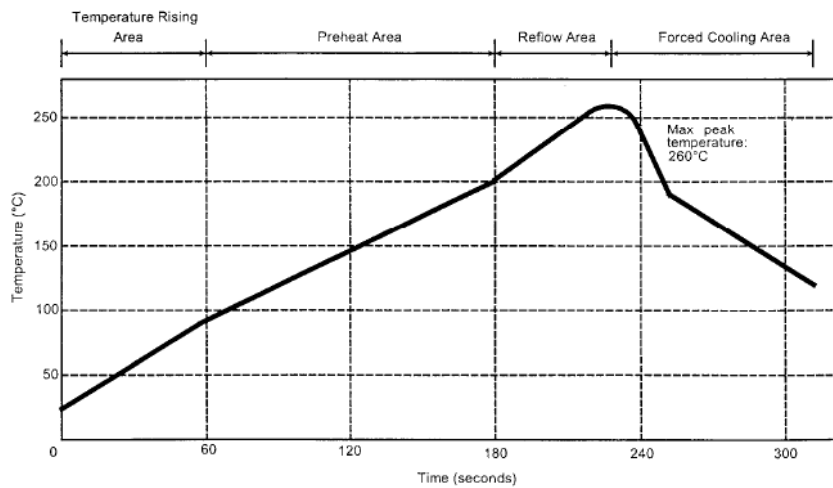
**R223.424.870**

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**SOLDER PROCEDURE**

1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.  
We advise a thickness of 150 micromm ( 5.850 microinch ). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
3. Soldering by infra-red reflow.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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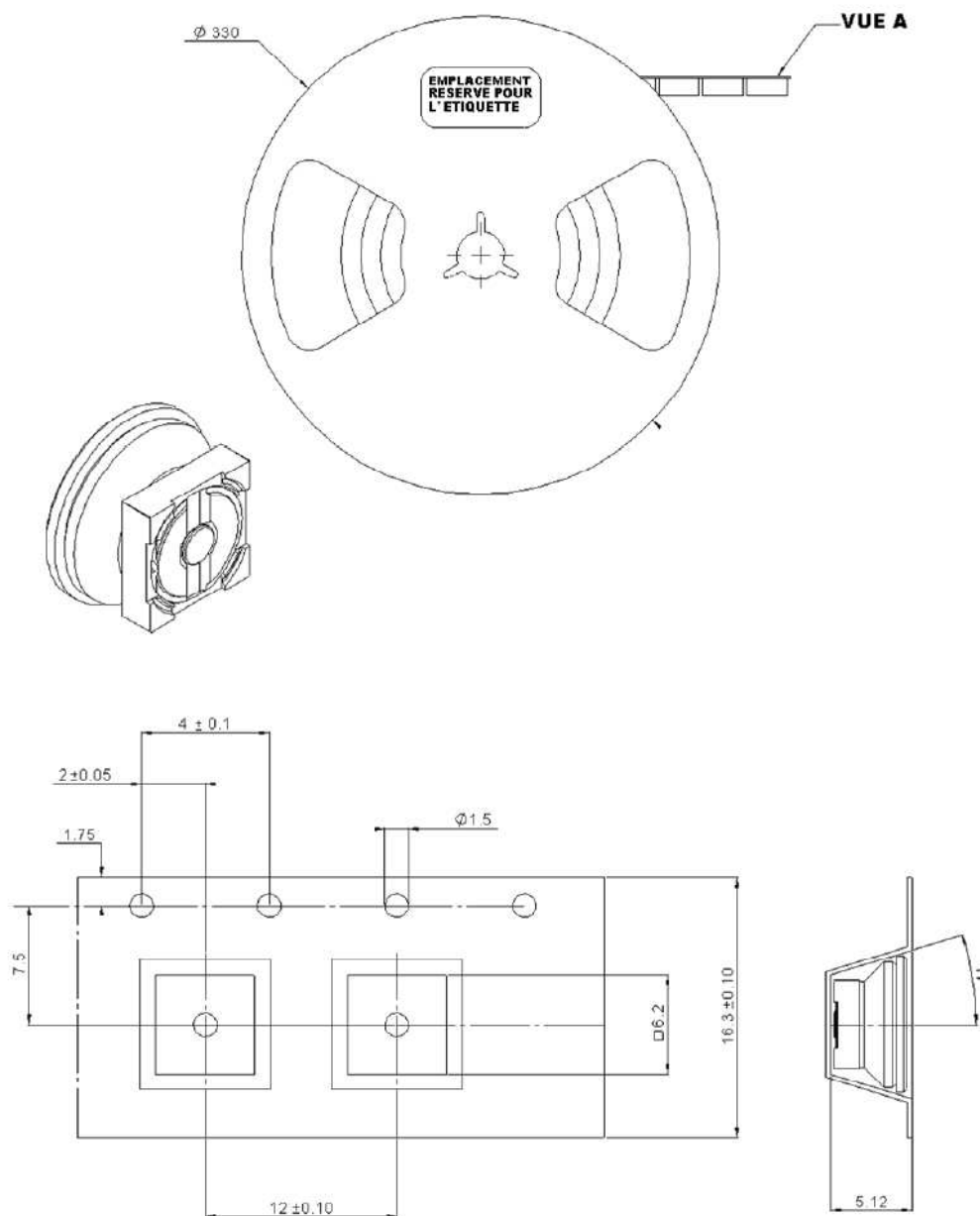
SMT JACK RECEPTACLE

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# MMBX SERIES INFORMATIONS



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